Dual N-Channel Enhancement Mode MOSFET

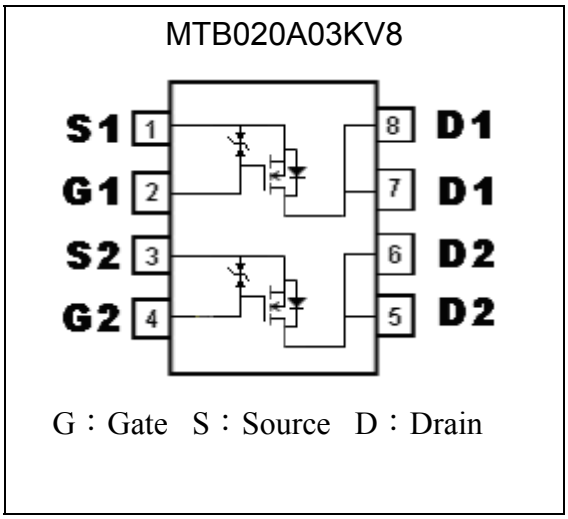
MTB020A03KV8

BV_{DSS}	30V
I_D@V_{GS}=10V, T_A=25°C	6.6A
I_D@V_{GS}=10V, T_C=25°C	12A
R_{DSON}@V_{GS}=10V typ.	15.2 mΩ
R_{DSON}@V_{GS}=4.5V typ.	20.1 mΩ

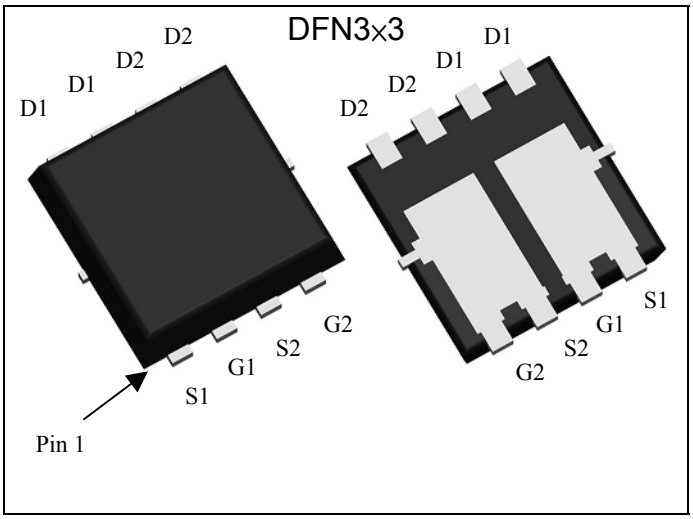
Features

- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Pb-free lead plating and halogen-free package

Equivalent Circuit

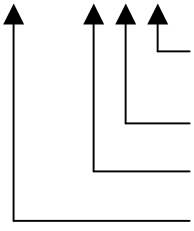


Outline



Ordering Information

Device	Package	Shipping
MTB020A03KV8-0-T6-G	DFN3x3 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel



Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T6 : 3000 pcs / tape & reel,13” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (TC=25°C, unless otherwise noted)

Parameter		Symbol	Limits	Unit
Drain-Source Breakdown Voltage		BVDSS	30	V
Gate-Source Voltage		VGS	±16	
Continuous Drain Current *2	TA=25 °C, VGS=10V	IDSM	6.6	A
	TA=70 °C, VGS=10V		5.3	
Continuous Drain Current	TC=25 °C, VGS=10V	ID	12	
	TC=100 °C, VGS=10V		7.6	
Pulsed Drain Current * 3		IDM	48	
Total Power Dissipation	TA=25°C, Single device operation	PDSM	1.5 *2	W
	TA=70°C, Single device operation		0.96 *2	
	TA=25°C,Single device value at dual operation		1.24 *2	
	TA=70°C,Single device value at dual operation		0.79 *2	
	TC=25°C	PD * 1	5	
	TC=100°C		2	
Operating Junction and Storage Temperature Range		Tj; Tstg	-55~+150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Max. Thermal Resistance, Junction-to-ambient, single device operation	$R_{th,j-a}$	84 *2	°C/W
Max. Thermal Resistance, Junction-to-ambient, single device value at dual operation		101 *2	
Max. Thermal Resistance, Junction-to-case	$R_{th,j-c}$	25	

Note : 1.The power dissipation PD is based on TJ(MAX)=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

2. The value of RθJA is measured with the device mounted on 1 in²FR-4 board with 2 oz. copper, in a still air environment with TA=25°C, t≤5s. 216°C/W when mounted on a minimum pad of 2 oz. copper. The power dissipation PDSM is based on RθJA and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

3. Pulse width limited by junction temperature TJ(MAX)=150°C. Ratings are based on low duty cycles to keep initial TJ=25°C.

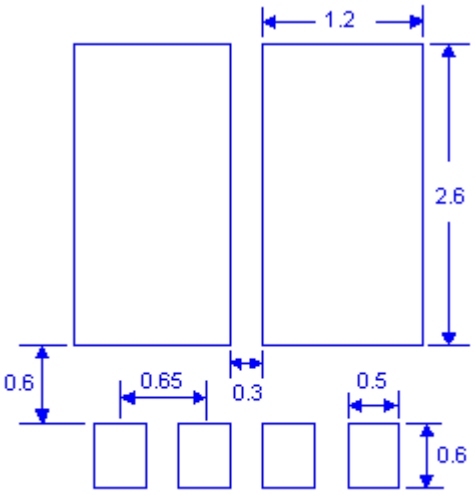
N-Channel Electrical Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BVDSS	30	-	-	V	VGS=0V, ID=250μA
VGS(th)	1	-	2.5		VDS=VGS, ID=250μA
IGSS	-	-	±10	μA	VGS=±16V, VDS=0V
IDSS	-	-	1		VDS=30V, VGS=0V
	-	-	10		VDS=24V, VGS=0V, Tj=70°C
*RDS(ON)	-	15.2	20	mΩ	VGS=10V, ID=10A
	-	20.1	28		VGS=4.5V, ID=8A
*GFS	-	3.6	-	S	VDS=10V, ID=1A

Dynamic					
Ciss	-	438	-	pF	V_{DS}=25V, V_{GS}=0V, f=1MHz
Coss	-	63	-		
Crss	-	47	-		
*$t_{d(ON)}$	-	5.8	-	ns	V_{DS}=15V, I_D=1A, V_{GS}=10V, R_G=6Ω
*t_r	-	17.2	-		
*$t_{d(OFF)}$	-	33.8	-		
*t_f	-	10.4	-		
*Qg	-	12.1	-	nC	V_{DS}=24V, I_D=10A, V_{GS}=10V
*Qgs	-	1.7	-		
*Qgd	-	3.6	-		
Body Diode					
*V_{SD}	-	0.8	1.2	V	V_{GS}=0V, I_S=2.3A
*trr	-	9.2	-	ns	I_S=2.3A, V_{GS}=0V, dI/dt=100A/μs
*Qrr	-	4	-	nC	

*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

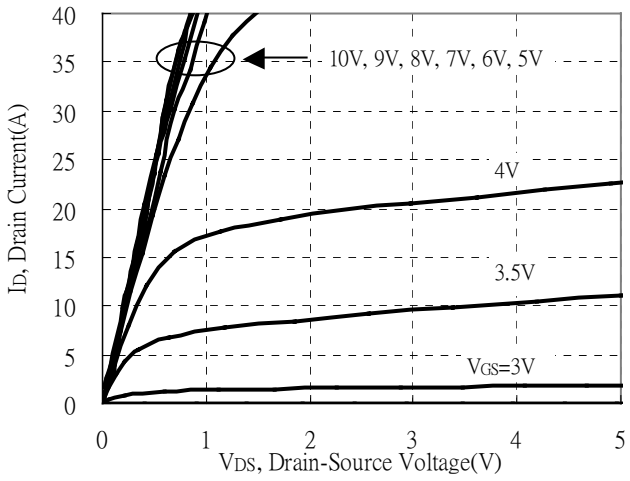
Recommended Soldering Footprint



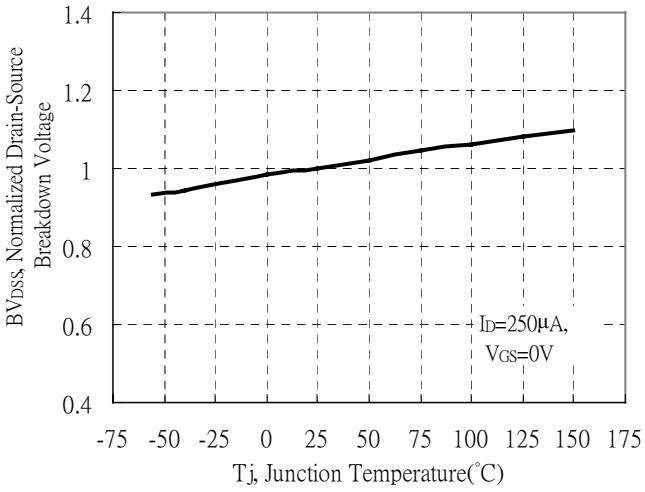
unit : mm

Typical Characteristics :

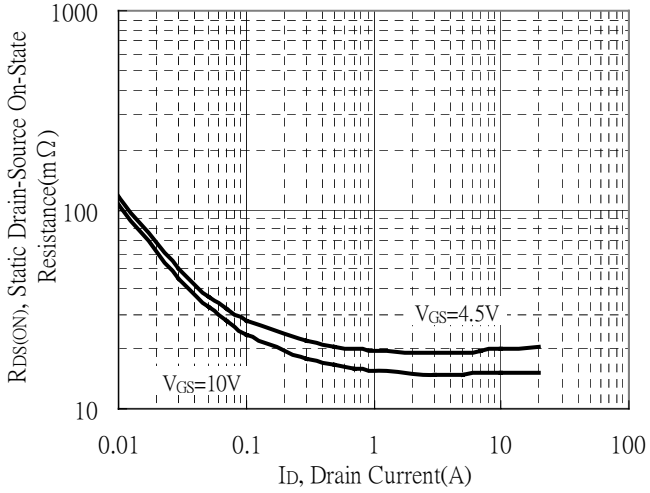
Typical Output Characteristics



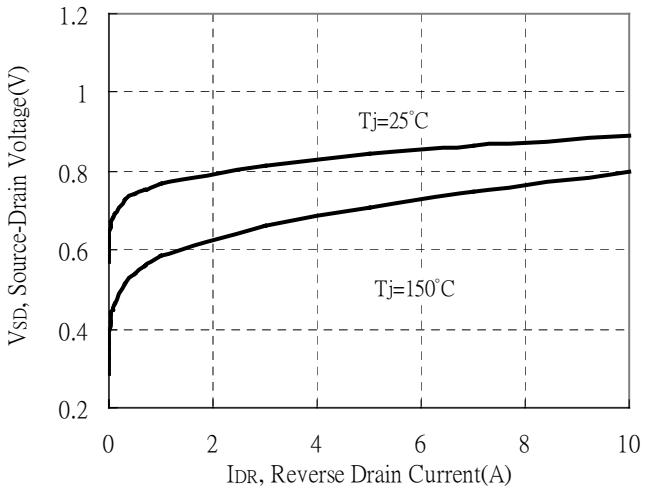
Brekdown Voltage vs Ambient Temperature



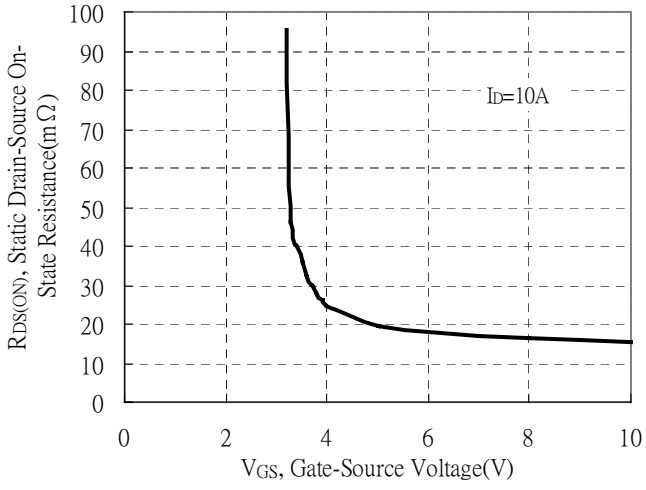
Static Drain-Source On-State resistance vs Drain Current



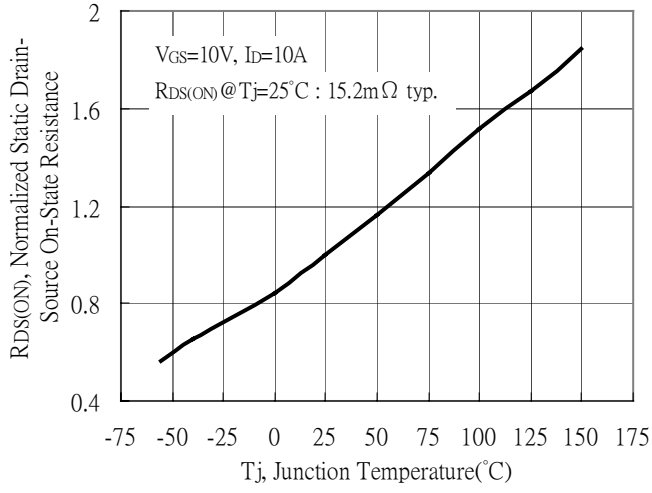
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

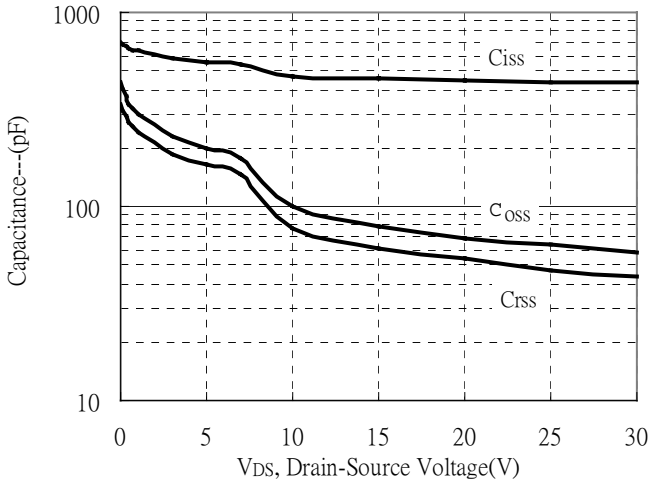


Drain-Source On-State Resistance vs Junction Tempearture

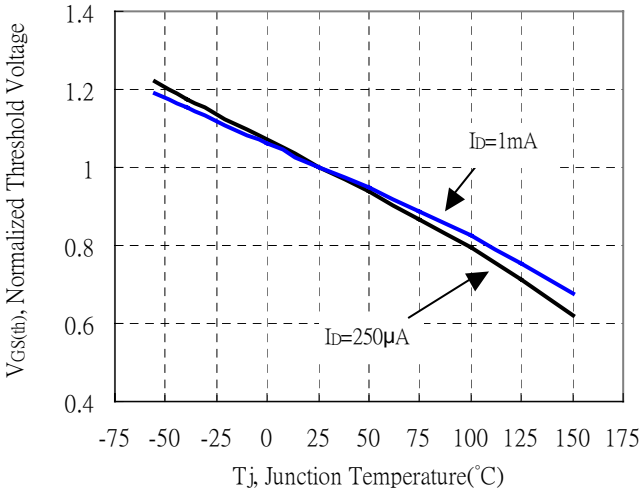


Typical Characteristics(Cont.) :

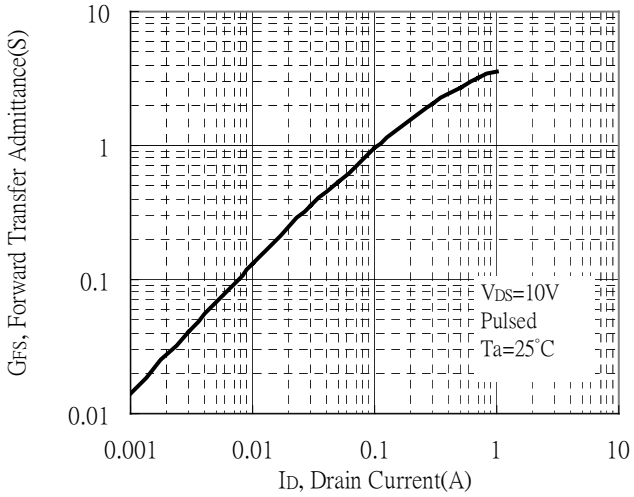
Capacitance vs Drain-to-Source Voltage



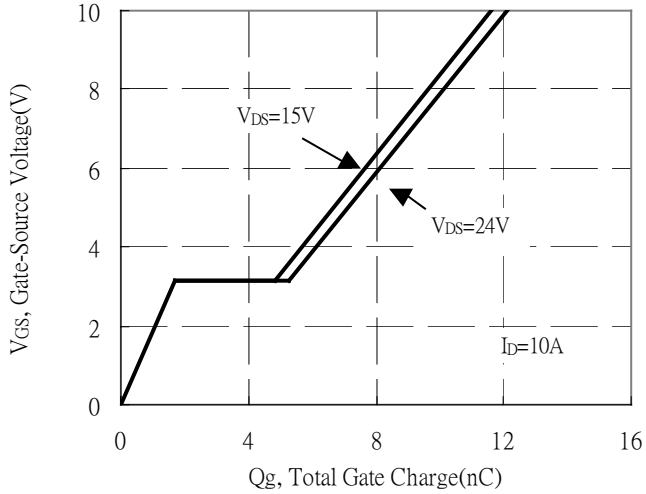
Threshold Voltage vs Junction Tempearture



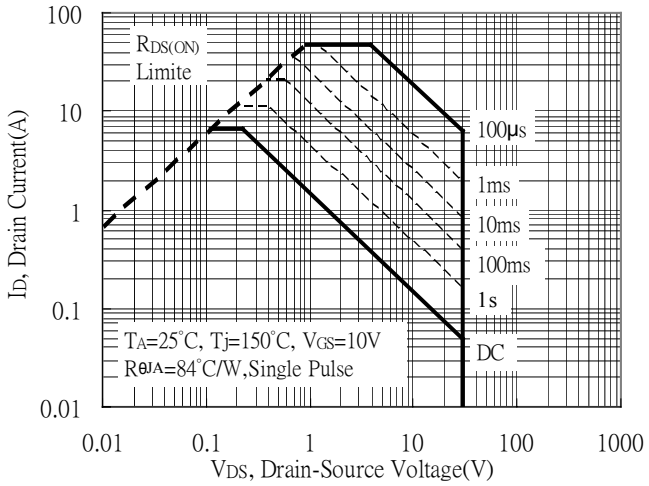
Forward Transfer Admittance vs Drain Current



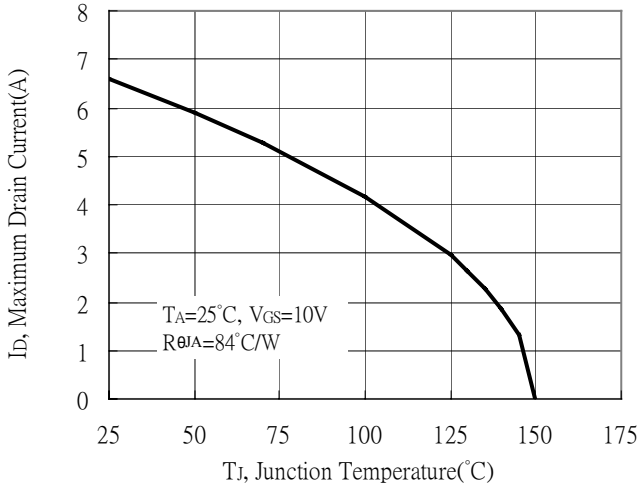
Gate Charge Characteristics



Maximum Safe Operating Area

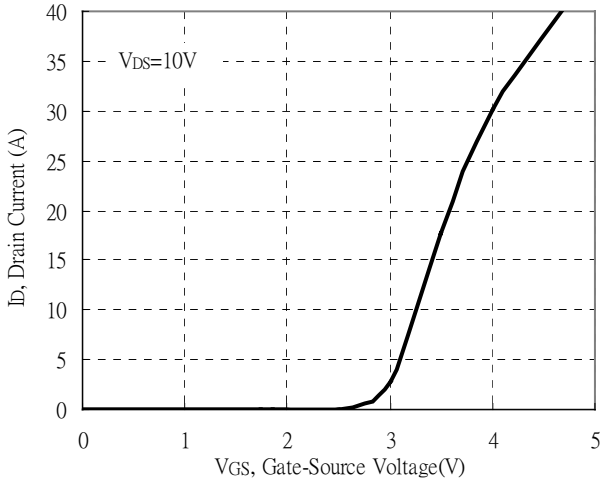


Maximum Drain Current vs Junction Temperature

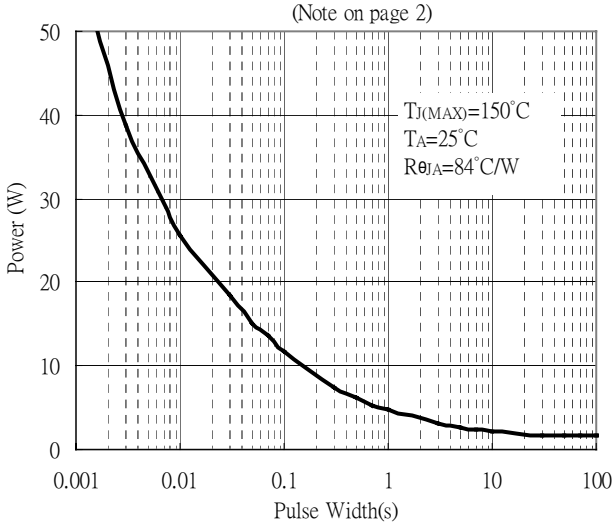


Typical Characteristics(Cont.) :

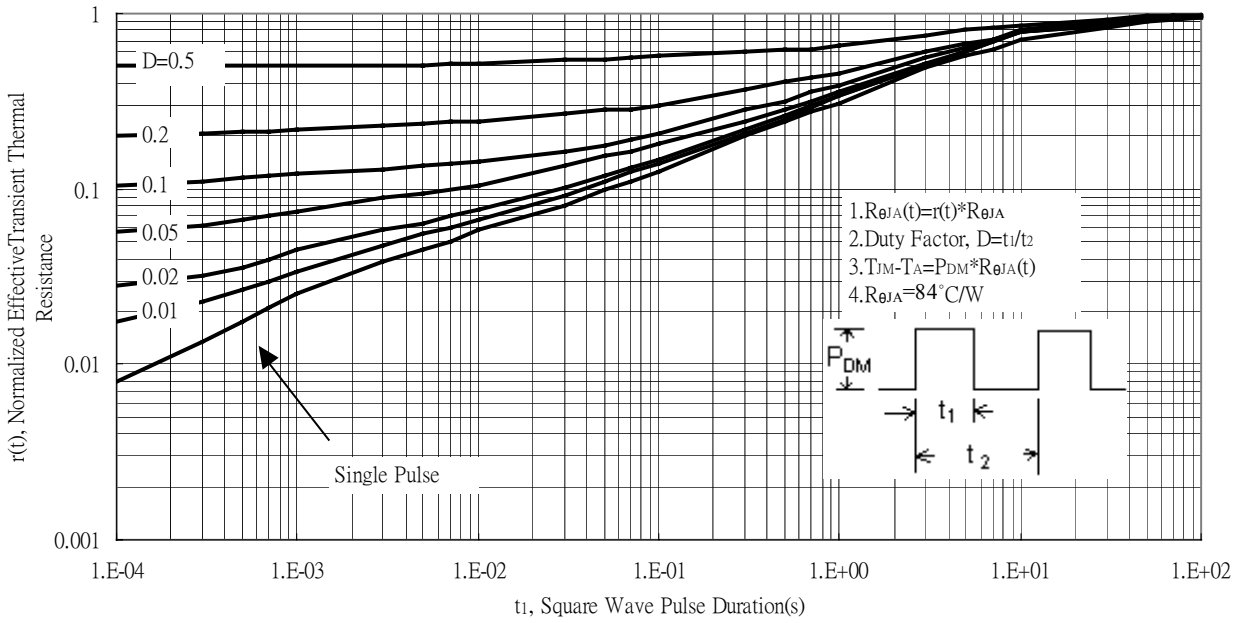
Typical Transfer Characteristics



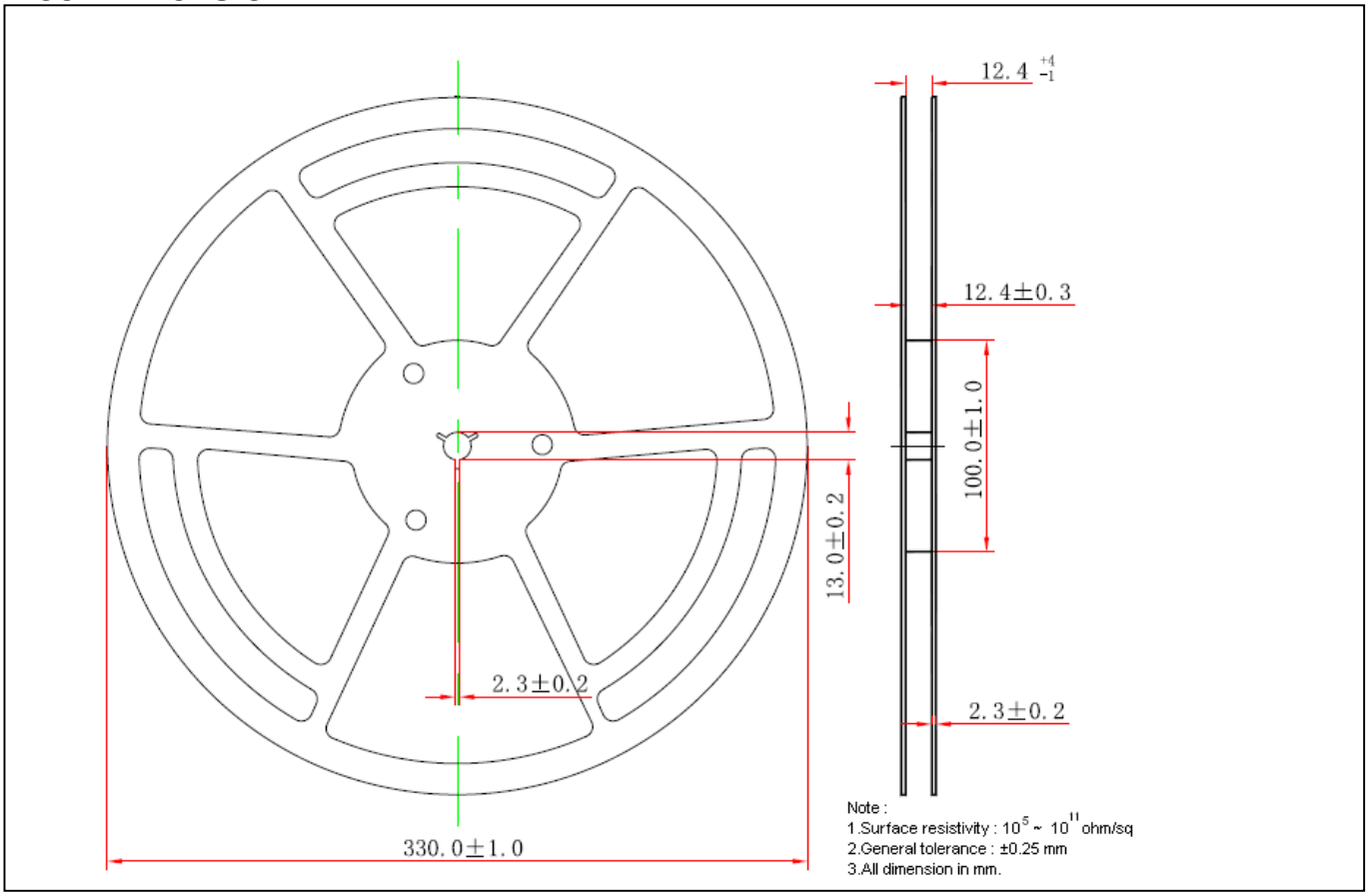
Single Pulse Power Rating, Junction to Ambient
(Note on page 2)



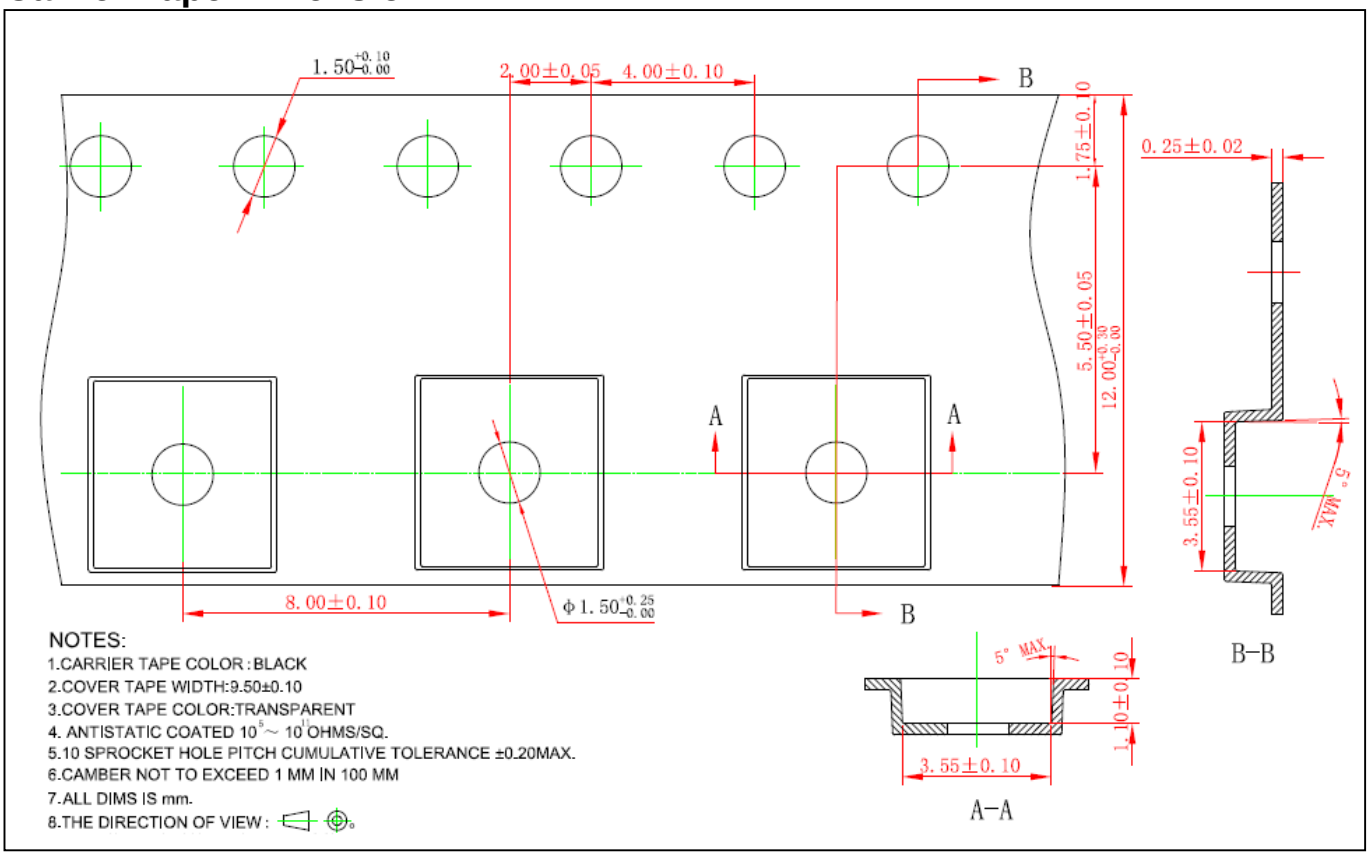
Transient Thermal Response Curves



Reel Dimension



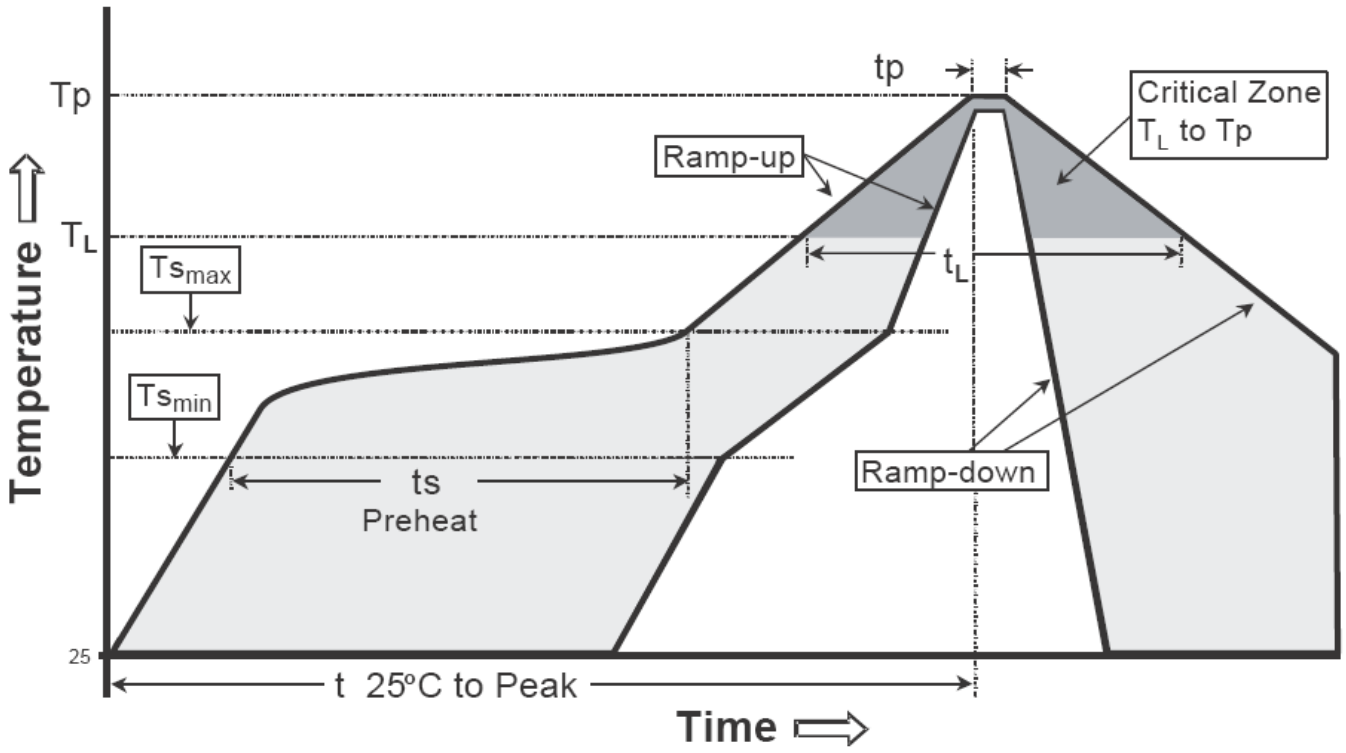
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

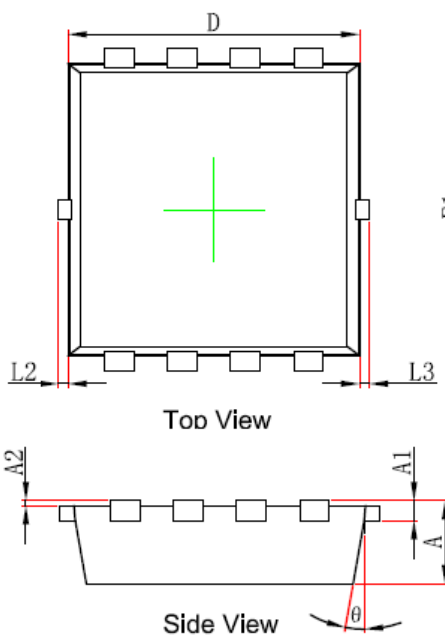
Recommended temperature profile for IR reflow

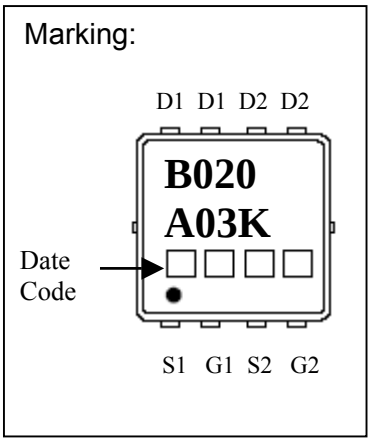


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time($t_{s\ min}$ to $t_{s\ max}$)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

DFN3x3 Dimension





8-Lead DFN3x3 Plastic Package
CYStek Package Code: V8

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033	b	0.200	0.400	0.008	0.016
A1	0.152 REF		0.006 REF		e	0.550	0.750	0.022	0.030
A2	0.000	0.050	0.000	0.002	L	0.300	0.500	0.012	0.020
D	2.900	3.100	0.114	0.122	L1	0.180	0.480	0.007	0.019
D1	0.935	1.135	0.037	0.045	L2	0.000	0.100	0.000	0.004
D2	0.280	0.480	0.011	0.019	L3	0.000	0.100	0.000	0.004
E	2.900	3.100	0.114	0.122	H	0.315	0.515	0.012	0.020
E1	3.150	3.450	0.124	0.136	θ	9°	13°	9°	13°
E2	1.535	1.935	0.060	0.076					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.